

ABSTRACT

A module includes an electronic component having at least two electrodes, a board having electrodes on its surface to be connected to the electrodes of the electronic component, respectively, solders for connecting
5 the electrodes of the electronic component to the electrodes of the board, respectively, an insulating resin covering the electronic component, the surface of the board, the solder, and the electrodes, and solder resists provided on the surface of the board and around the electrodes of the board, respectively. One of the solder resists is separated from the other electrode
10 at a portion between the electronic component and the board. When this module is mounted on a motherboard, the solder does not flow out of the electrodes even when the solder in the insulating resin melts.